

Bill of Materials

TI DESIGNS

TIPD127: Microcontroller PWM to 12bit Analog Out

Item #	Quantity	Designator	Value	Description	Manufacturer	PartNumber
1	6	+15V, -15V, S1_IN, S1_OUT, S2_IN, S2_OUT	N/A	TEST POINT PC MINI .040"D, Various Colors	Keystone	5000
2	1	C1	470n	CAP CER 0.47UF 50V 5% X7R 1210	Samsung	CL32B474JBFNNNE
3	1	C2	47n	CAP CER 0.047UF 50V 5% NP0 1210	TDK	C3225C0G1H473J200AA
4	1	C3	4.7n	CAP CER 4700PF 50V 5% NP0 1210	Samsung	CL32C472JBFNNNE
5	1	C4	470p	CAP CER 470PF 100V 5% NP0 1210	Murata	ERB32Q5C2A471JDX1L
6	2	C5, C6	NI	1210		
7	2	C7, C9	0.1u	CAP CER 0.1UF 50V 10% X7R 0603	Samsung	CL10B104KB8NNNC
8	2	C8, C10	10u	CAP CER 10UF 35V 10% X5R 1210	Samsung	CL32A106KLULNNE
9	2	C11, C13	100u	CAP CER 100UF 6.3V 20% X5R 1210	Kemet	C1210C107M9PACTU
10	1	C12	1p	CAP CER 1PF 50V NP0 0603	Samsung	CL10C010BB8NNNC
11	1	C14	10p	CAP CER 10PF 50V NP0 0603	Samsung	CL10C100CB8NNNC
12	6	GND0, GND3, GND4, GND5, GND6, GND7	5001	TEST POINT PC MINI .040"D BLACK	Keystone	5001
13	4	GND1, GND2, V+, V-	N/A	CONN JACK BANANA UNINS PANEL MOU	Emerson	108-0740-001
14	4	H1, H2, H3, H4	N/A	MACHINE SCREW PAN PHILLIPS 4-40	B&F Fastener	NY PMS 440 0025 PH
15	2	Input, Output	N/A	CONN SMA JACK R/A 50 OHM PCB	Amphenol	901-143-6RFX
16	1	J1	N/A	CONN HEADER 12POS .100" DL GOLD	Samtec	TSW-106-07-G-D
17	1	R1	50	RES 49.9 OHM 1/10W 1% 0603	Stackpole	RMCF0603FT49R9
18	1	R2	866	RES 866 OHM 1/10W 1% 0603 SMD	Panasonic	ERJ-3EKF8660V
19	1	R3	8.66k	RES 8.66K OHM 1/10W 1% 0603	Stackpole	RMCF0603FT8K66
20	1	R4	86.6k	RES 86.6K OHM 1/10W 1% 0603	Stackpole	RMCF0603FT86K6
21	1	R5	866k	RES 866K OHM 1/10W 1% 0603	Stackpole	RMCF0603FT866K
22	2	R6, R7	NI	0603		
23	1	R8	310k	RES 309K OHM 1/10W 1% 0603	Stackpole	RMCF0603FT309K
24	2	R9, R10	10k	RES 10K OHM 1/10W 1% 0603	Stackpole	RMCF0603FT10K0
25	1	R11	1k	RES 1K OHM 1/10W 1% 0603	Stackpole	RMCF0603FT1K00
26	1	R12	31k	RES 30.9K OHM 1/10W 1% 0603 SMD	Panasonic	ERJ-3EKF3092V
27	1	U1	N/A	Dual Op Amp	Texas Instruments	OPA2209AIDR

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